Silicom

Connectivity Solutions

uCPE Modular Universal CPE

uCPE Modular Universal CPE Based on Intel® Atom™ C3000

Product Description

Silicom's uCPE based on the Intel® Atom C3000 product line is a highly flexible yet low-cost network edge device that brings the agility of modular LAN, WAN, management, and compute to cost-sensitive applications in SD-WAN, CPE, security, small cell, and IoT.

With a new type of modularity designed specifically for cost and agility, uCPE is the ideal platform upon which to deploy next-generation edge applications.



Key Features

- Low-cost modular architecture consolidates multiple functions into a single box, reducing footprint, power, and complexity.
- Mix-and-match LAN, WAN, management, and compute modules allow uCPE features to be tailored to unique customer needs.
- Compliant with OCP uCPE 2.1 specifications.
- Silicom's MicroBMC provides secure remote management, software/firmware update, and phone home zero touch provisioning.

Technical Specifications

General Technical Specifications		
CPU	C3558, 4 cores, Base Freq. 2.2GHz, 8MB, TDP 16W	
BIOS	Coreboot	
BIOS Flash	SPI	
Operating System	Support Linux, ship without OS	
Memory	8GB Memory Down with ECC. (Platform supports up to 16GB memory down and an optional SODIMM that also supports up to 16GB)	
Storage	64GB eMMC	
Internal Switch	2x2.5Gb KR between CPU and Switch 1x1GbE between uBMC and Switch	
External port Switch	Marvell 88E6190X (X required for SFP) 4x1GbE 2x1GbE (POE+) 2xSFP	

Host Mgmt.	1GbE RJ45 on Management Card. Shared with BMC. Intel i210. 1GbE Between uBMC and Switch	
USB 3.0	2xFront, 2xInternal	
Serial Console	RJ45 RS232 Console	
LTE	M.2 Key-B, support 3042 Card. Externally accessible SIM card supported. Or Mini PCIe slot with externally accessible SIM card. LTE, is not part of BOM.	
WiFi	Mini PCIe Slot for WiFi. Wifi is not part of BOM,	
M.2 Expansion	M.2 Key B with support up to 30x110mm. Currently used for M.2 Storage Note: There is a board population option to support USB to the card for the possible IoT card. The default build option is not to support this feature.	
BMC	BMC. See uBMC specification for additional details	
ТРМ	TPM 2.0	
Power	12V@60W External Power Adapter with locking connector. Dying Gasp supported on BMC 54V@65W External Power Adapter with locking connector for POE+ ports	
LED's	Management card support three tri-color configurable LED's (red, green, blue)	
Form Factor	Desktop Form Factor (WxDxH) = 223x305x44mm Supports two side by side in 19" rack Rack Mount Option Wall Mount Option Branding Option	
Weight	2.2kg (77.60oz) without optical modules	
Power Consumption	Maximum • Input 1:110Vac / 1.8A ~ 240Vac / 0.8A, 50Hz to 60Hz • Output 1: 12V / 5A • Input 2: 110Vac / 1.8A ~ 240Vac / 1.2A, 50Hz to 60Hz Output 2: 54V / 1.2A Typical: • Input 1:110Vac / 0.47A ~ 240Vac / 0.3A, 50Hz to 60Hz • Output 1: 12V / 2.12A • Input 2: 110Vac / 1.2A ~ 240Vac / 0.8A, 50Hz to 60Hz Output 2: 54V / 1.1A	
Cooling	The total power consumption of the card depends on user application 12VDC 40mmx40mmx20mm 10.1 CFM FAN. Built-in thermal protection	
Sensors/Monitors	Thermal monitors Critical Error Detection Voltage monitors Current protection	
Operating Temperature	0°C – 40°C (32°F – 104°F)	
Storage	-40°C–65°C (-40°F–149°F)	
Regulation	CE EN 55032: 2012 + AC: 2013; EN55024: 2010, FCC Subpart B Class B, CB Scheme IEC 60950-1:2005 (second Edition) + Am 1:2009 + Am 2:2013, ROHS requirements	
MTBF*	143887.77 hours * According to Telcordia SR-332 Issue 4. Environmental condition – GB (Ground, Fixed, and Controlled). Ambient temperature 40°C	

Order Information

Silicom has available standard configuration uCPE systems for immediate customer usage. uCPE is easily reconfigured and customized across a wide range of customer specifications during production.

P/N	Description	Notes
80500-0150-G05	Shippable Kit: uCPE, Desktop, XS Module, Empty Right Slot, C3558 (4C), DDR4 8GB ECC, EMMC 64GB, including +12V, +54V Power supplies	Top level – Shippable kit, including packaging, GA